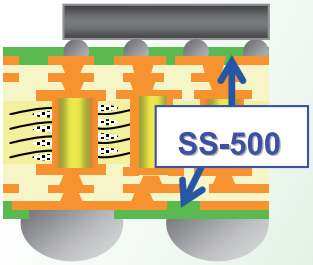
SS-500V2 (Trial＃65211)

LDA 用熱硬化型ソルダーレジストドライフィルム
Thermal curable Dry Film Solder Resist for LDA Application

主な特徴 Feature

- **高 Tg ／低 CTE 材　：他の PKG 用部材との熱挙動のマッチング**
  High Tg / Low CTE matched thermal behavior characteristic with other PKG materials
- **優れた電気特性／ PCT 耐性**
  Excellent electrical property and PCT resistance
- **レーザー光源の選択による、短時間での小径／大径 SRO 加工対応**
  Facilitating small / large diameter SRO in a short time by choice of laser light source
- **標準プロセスは、 内層材プロセスおよびドライデスミアプロセス対応**
  Standard process facilitates interlayer material / dry desmear process



仕様　Specification

膜厚　Thickness	20μm (Standard) – Adjustable
色調　Color	Green
保管条件　Storage condition	Below -15℃
標準硬化条件　Standard cure condition	170℃／ 60min

特性　Properties

ガラス転移点　Tg　＊TMA method	165-175℃
線膨脹係数　CTE　α1	20-25ppm
弾性率　Young`s modulus	7.5-8.0GPa
破断点強度　Tensile strength	100-110MPa
伸び　Elongation	2.0-3.0%
PCT 耐性　resistance (121℃/2atm/100%RH/200hrs)	No peeling
HAST 耐性　resistance (130℃/85%,12V,L/S=15/10μm)	＞400hrs (SR T=15μm,n=6,MTTF60%)

レーザー光源による SRO 加工性比較 (SR Thickness=20μm)
Comparison of SRO workability by laser light sources

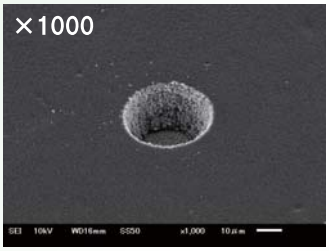


Fig. Top φ 30μm by UV-YAG
Equipment :Hitachi via mechanics
Process time : 740holes/sec

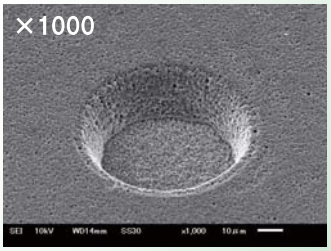


Fig. Top φ 65μm by CO2 laser
Equipment :Hitachi via mechanics
Process time : 800holes/sec

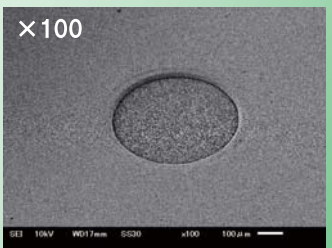


Fig. Top φ 500μm by CO2 laser
Equipment : Mitsubishi Electric
Process time : 380holes/sec

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